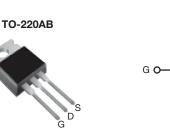


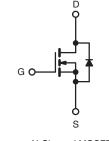
Vishay Siliconix



Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	800				
R _{DS(on)} (Ω)	V _{GS} = 10 V 3.0				
Q _g (Max.) (nC)	78				
Q _{gs} (nC)	9.6				
Q _{gd} (nC)	45				
Configuration	Single				





N-Channel MOSFET

FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- · Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFBE30PbF
	SiHFBE30-E3
SnPb	IRFBE30
	SiHFBE30

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	800	v	
Gate-Source Voltage			V _{GS}	± 20		
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C		4.1		
Continuous Drain Current	V _{GS} at 10 V	T _C = 100 °C	I _D	2.6	А	
Pulsed Drain Current ^a			I _{DM}	16	1	
Linear Derating Factor				1.0	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	260	mJ	
Repetitive Avalanche Current ^a			I _{AR}	4.1	А	
Repetitive Avalanche Energy ^a			E _{AR}	13	mJ	
Maximum Power Dissipation	T _C = 25 °C		PD	125	W	
Peak Diode Recovery dV/dt ^c			dV/dt	2.0	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s			300 ^d		
Mounting Torque	6-32 or M3 screw			10	lbf ∙ in	
Mounting Torque				1.1	N·m	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 29 mH, $R_q = 25 \Omega$, $I_{AS} = 4.1$ A (see fig. 12).

c. $I_{SD} \le 4.1$ A, dI/dt ≤ 100 A/µs, $V_{DD} \le 600$, $T_J \le 150$ °C.

d. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		62 - 1.0				
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50				°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	-						
SPECIFICATIONS (T _J = 25 °C, u	Inless otherw	ise noted)						
PARAMETER	SYMBOL			MIN.	TYP.	MAX.	UNIT	
Static								l
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	0 V, I _D = 2	250 μA	800	-	-	v
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			$I_D = 1 \text{ mA}$	-	0.9	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}		V_{GS} , $I_D = 2$		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}		$I_{GS} = \pm 20$		-	-	± 100	nA
		-	800 V, V _G		-	-	100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 640 V	V _{GS} = 0 V	′, T _J = 125 °C	-	-	500	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	١	₀ = 2.5 A ^b	-	-	3.0	Ω
Forward Transconductance	g fs	V _{DS} = 100 V, I _D = 2.5 A ^b		2.5	-	-	S	
Dynamic								
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	1300	-	pF	
Output Capacitance	C _{oss}			-	310	-		
Reverse Transfer Capacitance	C _{rss}			-	190	-		
Total Gate Charge	Qg			-	-	78		
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 4.1 \text{ A}, V_{DS} = 400 \text{ V},$		-	-	9.6	nC
Gate-Drain Charge	Q _{gd}	-	see f	see fig. 6 and 13 ^b		-	45	
Turn-On Delay Time	t _{d(on)}				-	12	-	
Rise Time	t _r	V_{DD} = 400 V, I_D = 4.1 A R_g = 12 Ω,R_D = 95 $\Omega,\text{see fig. }10^b$		-	33	-	ns	
Turn-Off Delay Time	t _{d(off)}			-	82	-		
Fall Time	t _f			-	30	-		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-		
Internal Source Inductance	L _S			-	7.5	-	nH	
Drain-Source Body Diode Characteristic	cs							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	4.1	A	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	16	~	
Body Diode Voltage	V_{SD}	T _J = 25 °C,	I _S = 4.1 A	, $V_{GS} = 0 V^{b}$	-	-	1.8	V
Body Diode Reverse Recovery Time	t _{rr}	- T _J = 25 °C, I _F = 4.1 A, dl/dt = 100 A/μs ^b		-	480	720	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.8	2.7	μC	
Forward Turn-On Time	t _{on}	Intrinsic tur	n-on time i	is negligible (turn	-on is dor	ninated b	y L _S and	L _D)

Notes

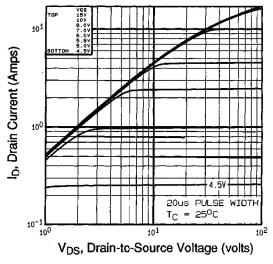
a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width \leq 300 $\mu s;$ duty cycle \leq 2 %.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



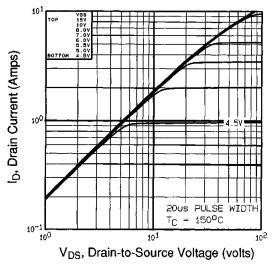
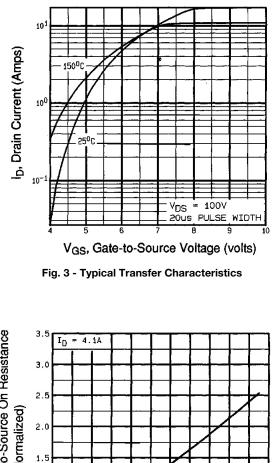


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C



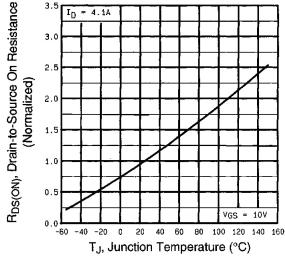


Fig. 4 - Normalized On-Resistance vs. Temperature

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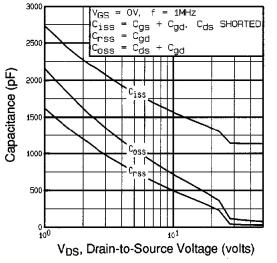
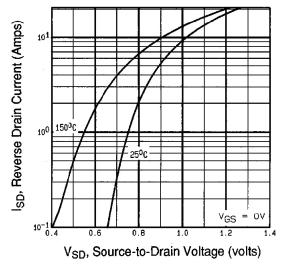
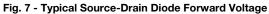


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





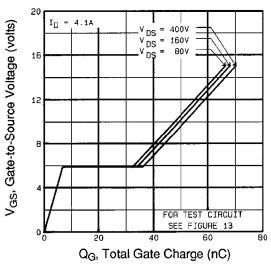
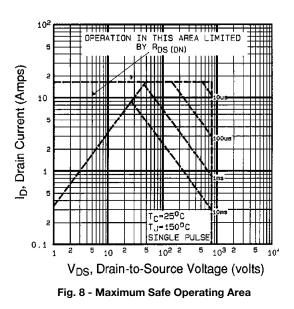


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



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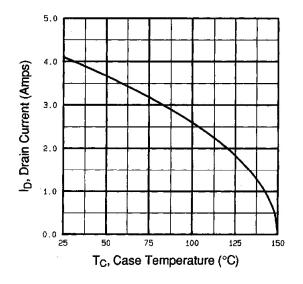


Fig. 9 - Maximum Drain Current vs. Case Temperature

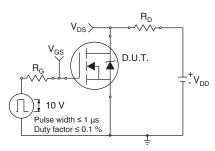


Fig. 10a - Switching Time Test Circuit

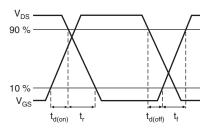


Fig. 10b - Switching Time Waveforms

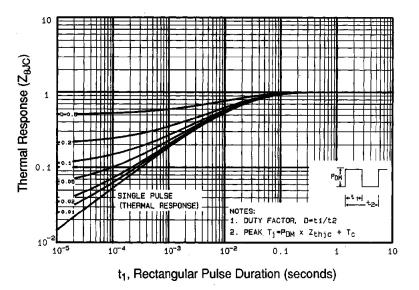


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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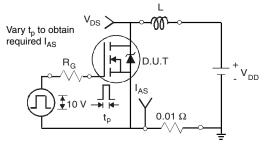


Fig. 12a - Unclamped Inductive Test Circuit

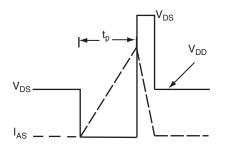


Fig. 12b - Unclamped Inductive Waveforms

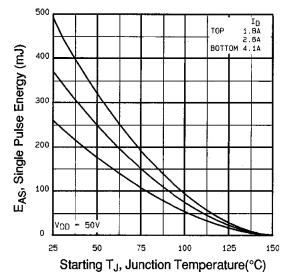


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

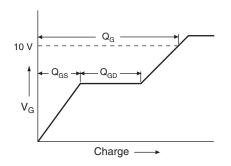


Fig. 13a - Basic Gate Charge Waveform

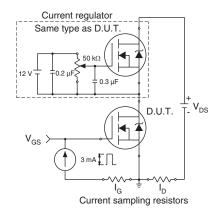


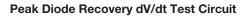
Fig. 13b - Gate Charge Test Circuit

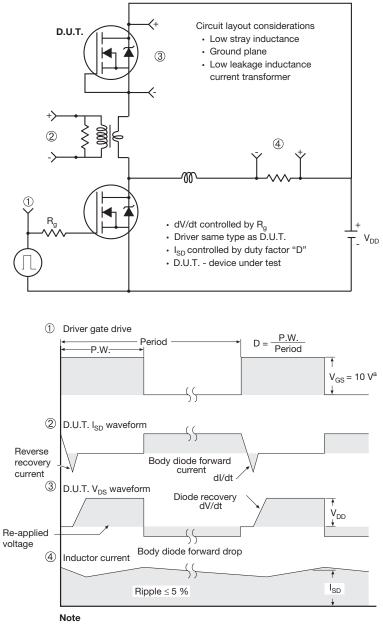
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a. V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

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TO-220AB



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
	0413-Rev. P,		0.102	0.118	

Note

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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